

Features

- Split Gate Trench MOSFET Technology
- Excellent Package for Heat Dissipation
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device ^(Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

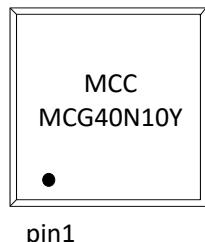
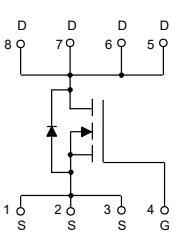
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 55°C/W Junction to Ambient ^(Note2)
- Thermal Resistance: 2.9°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current T _C =25°C	I _D	40	A
T _C =100°C		25	
Pulsed Drain Current ^(Note3)	I _{DM}	160	A
Total Power Dissipation ^(Note4)	P _D	43	W
Single Pulsed Avalanche Energy ^(Note5)	E _{AS}	81	mJ

Note:

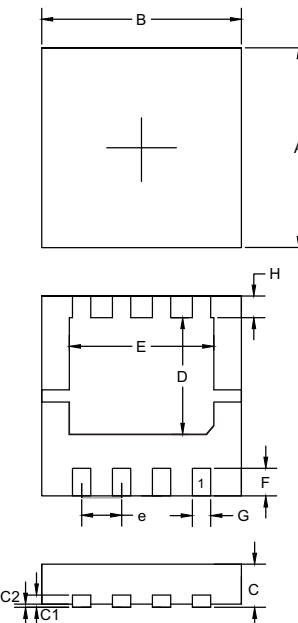
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. T_J=25°C, V_{DD}=50V, V_{GS}=10V, R_G=25Ω, L=0.5mH.

Internal Structure and Marking Code



N-CHANNEL MOSFET

DFN3333



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	0.126	0.130	3.20	3.30	
B	0.126	0.130	3.20	3.30	
C	0.030	0.033	0.75	0.85	
C1	0.007	0.009	0.18	0.22	
C2	---	0.002	---	0.05	
D	0.071	0.079	1.80	2.00	
E	0.087	0.098	2.20	2.50	
F	0.016	0.020	0.40	0.50	
G	0.010	0.014	0.25	0.35	
H	0.012	0.016	0.30	0.40	
e	0.024	0.028	0.60	0.70	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.8	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		15	18.5	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$		18	22.5	
Gate Resistance	R_g	f=1 MHz, Open drain		1.2		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				40	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=20A$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F=20A, dI_F/dt=100A/\mu s$		42		ns
Reverse Recovery Charge	Q_{rr}			47		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		1139		pF
Output Capacitance	C_{oss}			426		
Reverse Transfer Capacitance	C_{rss}			11		
Total Gate Charge	Q_g	$V_{DS}=50V, V_{GS}=10V, I_D=25A$		18		nC
Gate-Source Charge	Q_{gs}			3.2		
Gate-Drain Charge	Q_{gd}			3.5		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_G=2.2\Omega, I_{DS}=25A$		7		ns
Turn-On Rise Time	t_r			3		
Turn-Off Delay Time	$t_{d(off)}$			17		
Turn-Off Fall Time	t_f			3		

Curve Characteristics

Fig.1 - Typical Output Characteristics

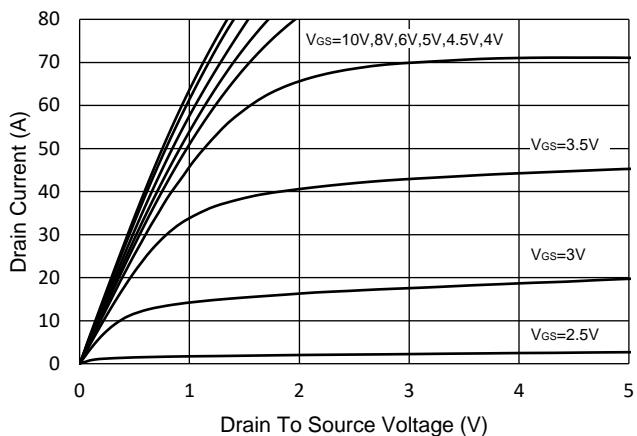


Fig.2 - Transfer Characteristic

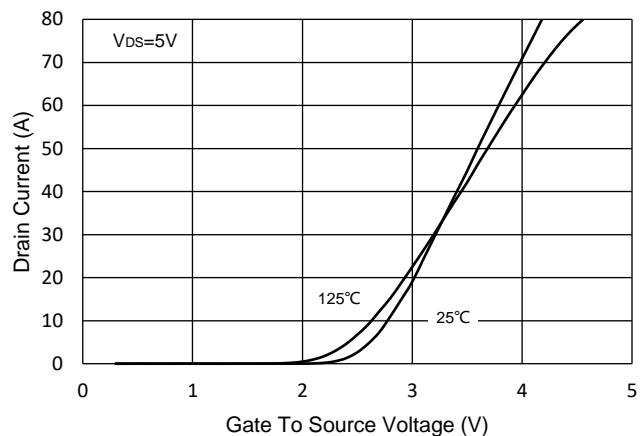


Fig.3 - $R_{DS(ON)}$ - V_{GS}

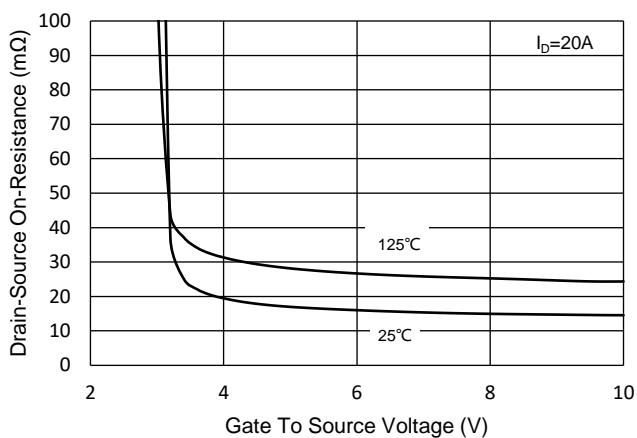


Fig.4 - $R_{DS(ON)}$ - I_D

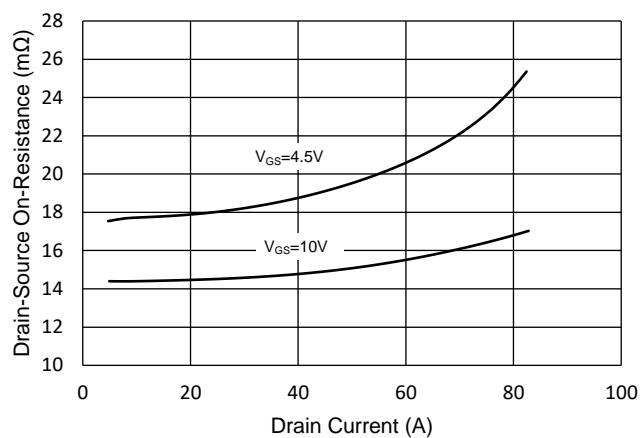


Fig.5 - Capacitance Characteristics

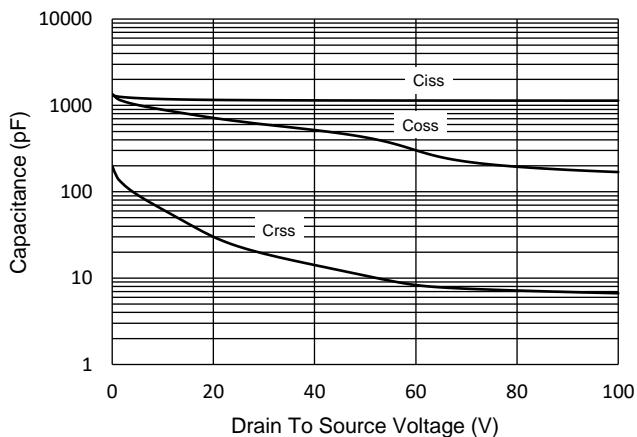
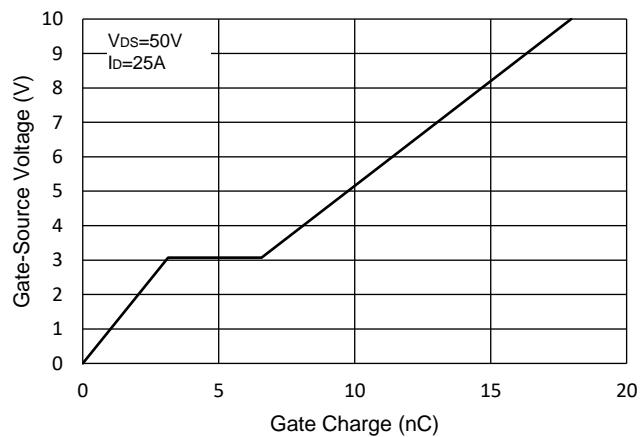


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

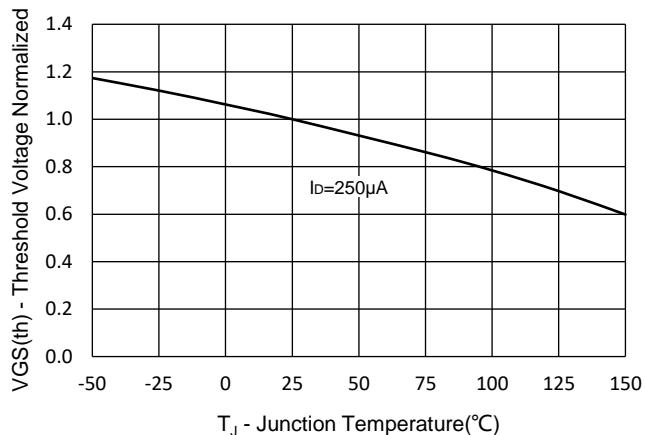


Fig.8 - Normalized On Resistance Characteristics

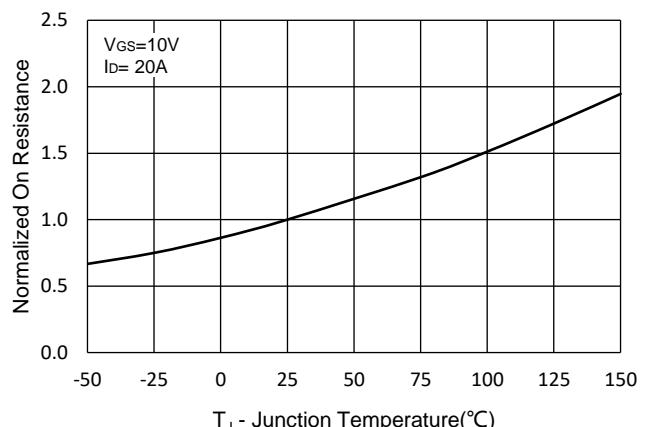


Fig.9 - I_S - V_{SD}

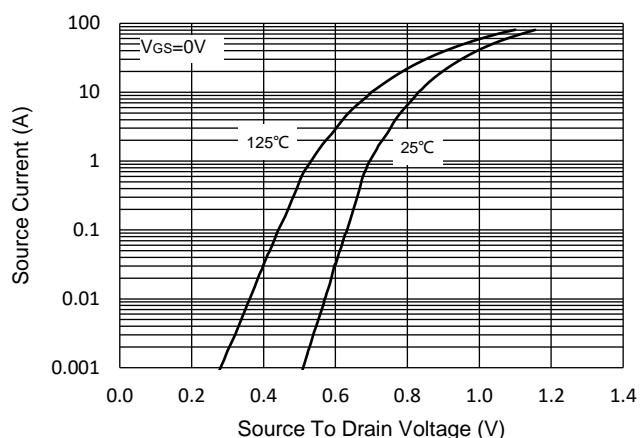


Fig.10 - Drain Current

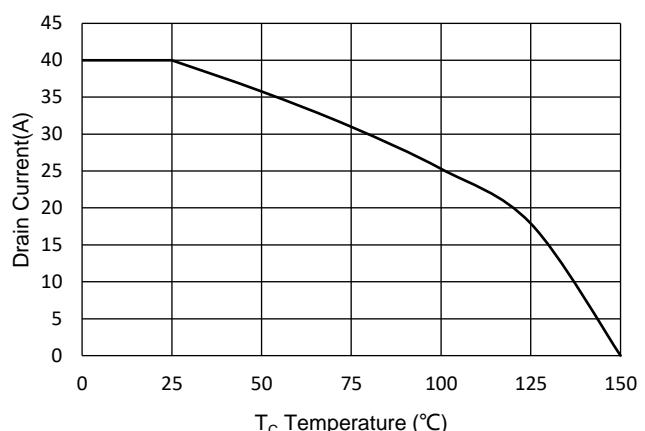
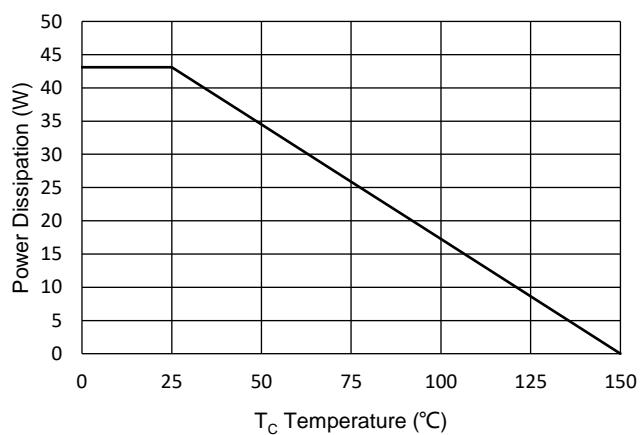


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

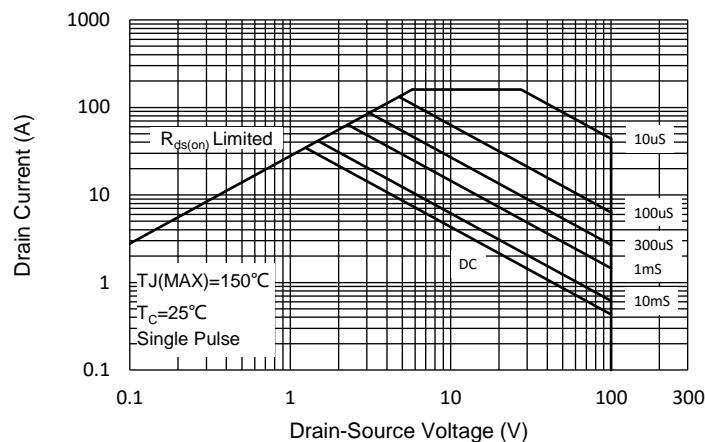
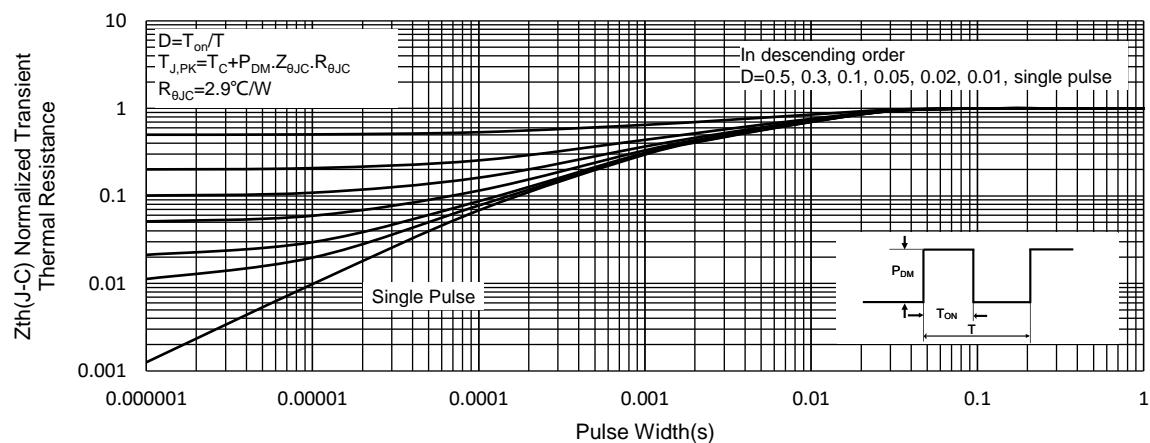


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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